Chapter 4. Serial Configuration Devices (EPCS1, EPCS4, EPCS16 & EPCS64) Data Sheet

Features

The serial configuration devices provide the following features:

- 1-, 4-, 16-, and 64-Mbit flash memory devices that serially configure Stratix® II FPGAs and the Cyclone™ series FPGAs using the active serial (AS) configuration scheme
- Easy-to-use four-pin interface
- Low cost, low pin count and non-volatile memory
- Low current during configuration and near-zero standby mode current
- 3.3-V operation
- Available in 8-pin and 16-pin small outline integrated circuit (SOIC) package
- Enables the Nios® processor to access unused flash memory through AS memory interface
- Re-programmable memory with more than 100,000 erase/program cycles
- Write protection support for memory sectors using status register bits
- In-system programming support with SRunner software driver
- Programming support with USB Blaster™ or ByteBlaster™ II download cables
- Additional programming support with the Altera® Programming Unit (APU) and programming hardware from BP Microsystems, System General, and other vendors
- Software design support with the Altera Quartus® II development system for Windows-based PCs as well as Sun SPARC station and HP 9000 Series 700/800
- Delivered with the memory array erased (all the bits set to 1)

☞ Whenever the term "serial configuration device(s)" is used in this document, it refers to Altera EPCS1, EPCS4, EPCS16, and EPCS64 devices.

Functional Description

With SRAM-based devices such as Stratix II FPGAs and the Cyclone series FPGAs, configuration data must be reloaded each time the device powers up, the system initializes, or when new configuration data is needed. Serial configuration devices are flash memory devices with a

serial interface that can store configuration data for a Stratix II FPGA or a Cyclone series device and reload the data to the device upon power-up or reconfiguration. Table 4–1 lists the serial configuration devices.

Table 4–1. Serial Configuration Devices (3.3-V Operation)	
Device	**Memory Size (Bits)**
EPCS1	1,048,576
EPCS4	4,194,304
EPCS16	16,777,216 *(1)*
EPCS64	67,108,864 *(1)*

Note to Table 4–1:
(1)   This information is preliminary.

You can vertically migrate from the EPCS1 to the EPCS4 device since they are offered in the same device package. Similarly, you can vertically migrate from the EPCS16 to the EPCS64 device.

Table 4–2 lists the serial configuration device used with each Stratix II FPGA and the configuration file size. Stratix II devices can only be used with EPCS16 or EPCS64 devices.

Table 4–2. Serial Configuration Device Support for Stratix II Devices			
Stratix II Device	**Raw Binary File Size (Bits)** *(1)*	**Serial Configuration Device**	
		EPC16	**EPCS64**
EP2S15	5,000,000	✔	✔
EP2S30	10,100,000	✔	✔
EP2S60	17,100,000	✔ *(2)*	✔
EP2S90	27,500,000		✔
EP2S130	39,600,000		✔
EP2S180	52,400,000		✔

Notes to Table 4–2:
(1)   These are preliminary, uncompressed file sizes.
(2)   This is with the Stratix II compression feature enabled.

Table 4–3 lists the serial configuration device used with each Cyclone II FPGA and the configuration file size. Cyclone II devices can be used with all serial configuration devices.

Table 4–3. Serial Configuration Device for Cyclone II Devices

Cyclone II Device	Raw Binary File Size (Bits) *(1)*	Serial Configuration Device			
		EPCS1	EPCS4	EPCS16	EPCS64
EP2C5	1,223,980	✓ *(2)*	✓	✓	✓
EP2C8	1,983,792		✓	✓	✓
EP2C20	3,930,986		✓	✓	✓
EP2C35	7,071,234			✓	✓
EP2C50	9,122,148			✓	✓
EP2C70	10,249,694			✓	✓

Notes to Table 4–3:
(1)   These are preliminary, uncompressed file sizes.
(2)   This is with the Cyclone II compression feature enabled.

Table 4–4 lists the serial configuration device used with each Cyclone FPGA and the configuration file size. Cyclone devices can only be used with EPCS1, EPCS4, or EPCS16 devices.

Table 4–4. Serial Configuration Device Support for Cyclone Devices

Cyclone Device	Raw Binary File Size (Bits) *(1)*	Serial Configuration Device		
		EPCS1	EPCS4	EPCS16
EP1C3	627,376	✓	✓	✓
EP1C4	925,000	✓	✓	✓
EP1C6	1,167,216	✓ *(2)*	✓	✓
EP1C12	2,326,528		✓	✓
EP1C20	3,559,608		✓	✓

Notes to Table 4–4:
(1)   These are preliminary, uncompressed file sizes.
(2)   This is with the Cyclone compression feature enabled.

With the new data-decompression feature in the Stratix II and Cyclone FPGA families, designers can use smaller serial configuration devices to configure larger FPGAs.

☞　　Serial configuration devices cannot be cascaded.

👣　　See *Configuring Stratix II Devices* in the Configuration Handbook for more information regarding the Stratix II FPGA decompression feature.

👣　　See *Configuring Cyclone II Devices* in the Configuration Handbook for more information regarding the Cyclone II FPGA decompression feature.

👣　　See *Configuring Cyclone FPGAs* in the Configuration Handbook for more information regarding the Cyclone FPGA decompression feature.

The serial configuration devices are designed to configure Stratix II FPGAs and the Cyclone series FPGAs and cannot configure other existing Altera device families.

Figure 4–1 shows the serial configuration device block diagram.

Figure 4–1. Serial Configuration Device Block Diagram
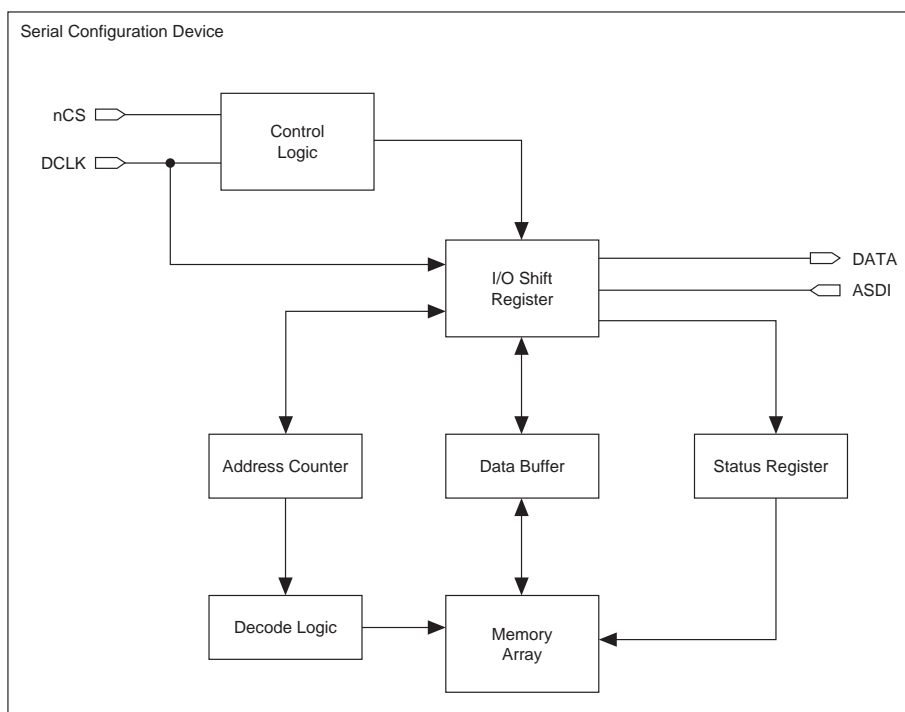
Accessing Memory in Serial Configuration Devices

You can access the unused memory locations of the serial configuration device to store or retrieve data through the Nios processor and SOPC Builder. SOPC Builder is an Altera tool for creating bus-based (especially microprocessor-based) systems in Altera devices. SOPC Builder assembles library components like processors and memories into custom microprocessor systems.

SOPC Builder includes the active serial memory interface (ASMI) peripheral, an interface core specifically designed to work with the serial configuration device. Using this core, you can create a system with a Nios embedded processor that allows software access to any memory location within the serial configuration device.

For more information on accessing memory within the serial configuration device, see the *Active Serial Memory Interface Data Sheet*.

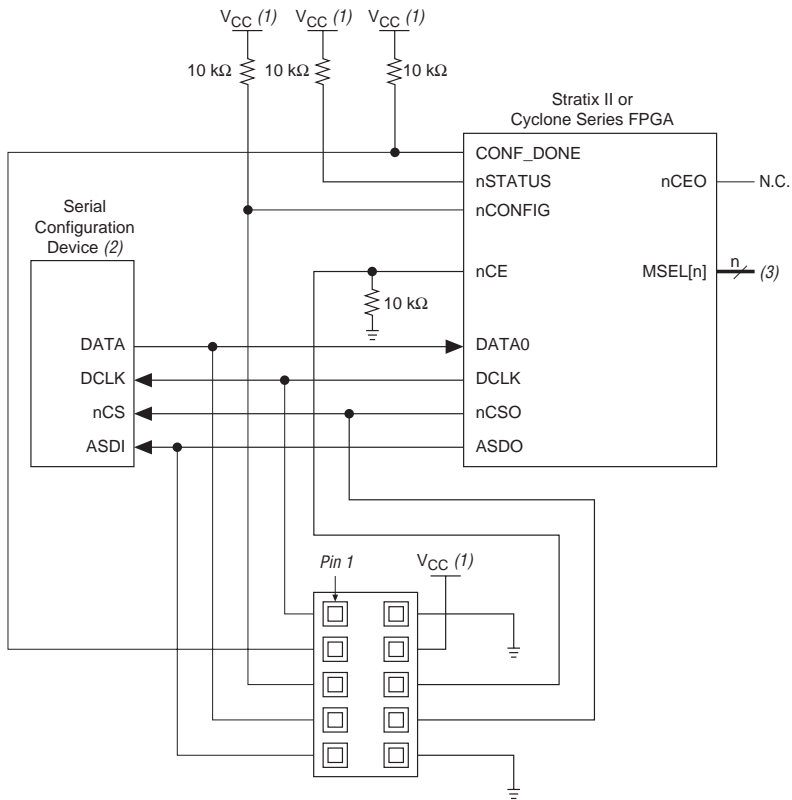# Active Serial FPGA Configuration

Stratix II FPGAs and the Cyclone series FPGAs can be configured with a serial configuration device through the AS configuration mode.

This section is only relevant for FPGAs that support the Active Serial (AS) configuration scheme. Only Stratix II FPGAs and the Cyclone series FPGAs support the AS configuration scheme.

There are four signals on the serial configuration device that interface directly with the FPGA's control signals. The serial configuration device signals DATA, DCLK, ASDI, and nCS interface with DATA0, DCLK, ASDO, and nCSO control signals on the FPGA, respectively. Figure 4–2 shows a serial configuration device programmed via a download cable which configures an FPGA in AS mode. Figure 4–3 shows a serial configuration device programmed using the APU or a third-party programmer configuring an FPGA in AS configuration mode.

Figure 4–2. FPGA Configuration in AS Mode (Serial Configuration Device Programmed Using Download Cable)

Figure 4–3. FPGA Configuration in AS Mode (Serial Configuration Device Programmed by APU or Third-Party Programmer)
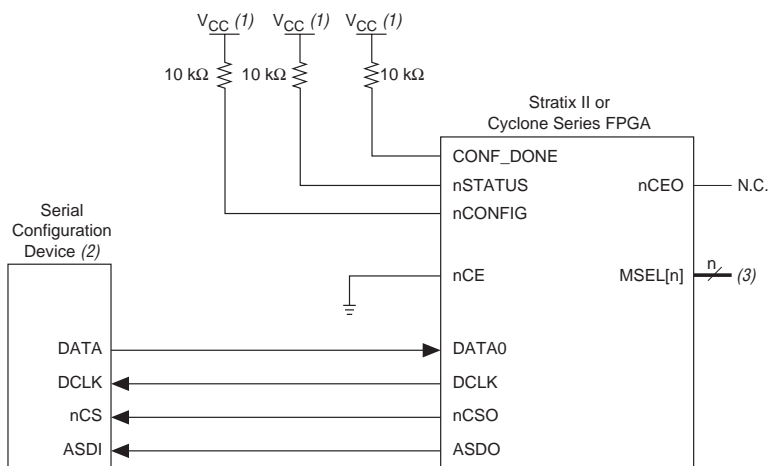
Notes to Figures 4–2 and 4–3:
(1) V_{CC} = 3.3-V.
(2)   Serial configuration devices cannot be cascaded.
(3)   Connect the FPGA MSEL[] input pins to select the AS configuration mode. For details, refer to the appropriate FPGA family chapter in the Configuration Handbook.

The FPGA acts as the configuration master in the configuration flow and provides the clock to the serial configuration device. The FPGA enables the serial configuration device by pulling the nCS signal low via the nCSO signal (See Figures 4–2 and 4–3). Subsequently, the FPGA sends the instructions and addresses to the serial configuration device via the ASDO signal. The serial configuration device responds to the instructions by sending the configuration data to the FPGA's DATA0 pin on the falling edge of DCLK. The data is latched into the FPGA on the DCLK signal's rising edge.

The FPGA controls the nSTATUS and CONF_DONE pins during configuration in AS mode. If the CONF_DONE signal does not go high at the end of configuration or if the signal goes high too early, the FPGA will pulse its nSTATUS pin low to start reconfiguration. Upon successful configuration, the FPGA releases the CONF_DONE pin, allowing the external 10-kΩ resistor to pull this signal high. Initialization begins after the CONF_DONE goes high. After initialization, the FPGA enters user mode.

For more information on configuring Stratix II FPGAs in AS mode or other configuration modes, see *Configuring Stratix II Devices* in the Configuration Handbook.

For more information on configuring Cyclone II FPGAs in AS mode or other configuration modes, see Chapter 4, Configuring Cyclone II Devices in the *Configuration Handbook, Volume 1*.

For more information on configuring Cyclone FPGAs in AS mode or other configuration modes, see Chapter 5, Configuring Cyclone FPGAs in the *Configuration Handbook, Volume 1*.

Multiple devices can be configured by a single EPCS device. However, serial configuration devices cannot be cascaded. Check Table 4–1 to ensure the programming file size of the cascaded FPGAs does not exceed the capacity of a serial configuration device. Figure 4–4 shows the AS configuration scheme with multiple FPGAs in the chain. The first Stratix II or Cyclone device is the configuration master and has its `MSEL[]` pins set to AS mode. The following FPGAs are configuration slave devices and have their `MSEL[]` pins set to PS mode.

Figure 4–4. Multiple Devices in AS Mode
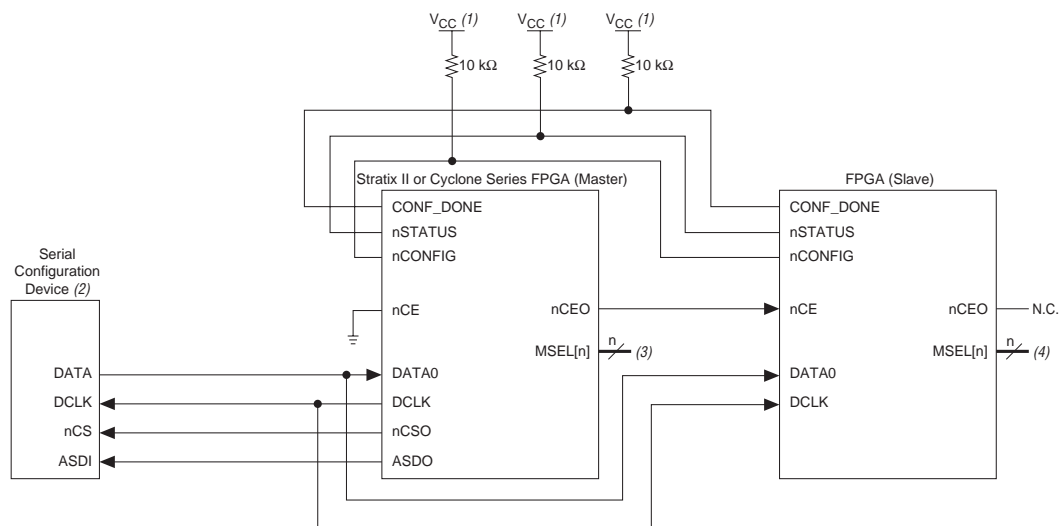
Notes to Figure 4–4:
(1) V_{CC} = 3.3-V.
(2) Serial configuration devices cannot be cascaded.
(3) Connect the FPGA `MSEL[]` input pins to select the AS configuration mode. For details, refer to the appropriate FPGA family chapter in the Configuration Handbook.
(4) Connect the FPGA `MSEL[]` input pins to select the PS configuration mode. For details, refer to the appropriate FPGA family chapter in the Configuration Handbook

Serial Configuration Device Memory Access

This section describes the serial configuration device's memory array organization and operation codes. Timing specifications for the memory are provided in the "Timing Information" section.

☞ Information on EPCS16 and EPCS64 devices will be available when devices are available.

Memory Array Organization

Table 4–5 provides details on the memory array organization in EPCS4 and EPCS1 devices.

Table 4–5. Memory Array Organization in Serial Configuration Devices

Details	EPCS4	EPCS1
Bytes (bits)	524,888 bytes (4 Mbits)	131, 072 bytes (1 Mbit)
Number of sectors	8	4
Bytes (bits) per sector	65,536 bytes (512 Kbits)	32,768 bytes (256 Kbits)
Pages per sector	256	128
Total number of pages	2,048	512
Bytes per page	256 bytes	256 bytes

Tables 4–6 and 4–7 show the address range for each sector in the EPCS4 and EPCS1 devices, respectively.

Table 4–6. Address Range for Sectors in EPCS4 Devices

Sector	Address Range (Byte Addresses in HEX)	
	Start	End
7	H'70000	H'7FFFF
6	H'60000	H'6FFFF
5	H'50000	H'5FFFF
4	H'40000	H'4FFFF
3	H'30000	H'3FFFF
2	H'20000	H'2FFFF
1	H'10000	H'1FFFF
0	H'00000	H'0FFFF

Table 4–7. Address Range for Sectors in EPCS1 Devices

Sector	Address Range (Byte Addresses in HEX)	
	Start	End
3	H'18000	H'1FFFF
2	H'10000	H'17FFF
1	H'08000	H'0FFFF
0	H'00000	H'07FFF

Operation Codes

This section describes the operations that can be used to access the memory in serial configuration devices. The DATA, DCLK, ASDI, and nCS signals access to the memory in serial configuration devices. All serial configuration device operation codes, addresses and data are shifted in and out of the device serially, with the most significant bit (MSB) first.

The device samples the active serial data input on the first rising edge of the DCLK after the active low chip select (nCS) input signal is driven low. Shift the operation code (MSB first) serially into the serial configuration device through the active serial data input pin. Each operation code bit is latched into the serial configuration device on the rising edge of the DCLK.

Different operations require a different sequence of inputs. While executing an operation, you must shift in the desired operation code, followed by the address bytes, data bytes, both, or neither. The device must drive nCS high after the last bit of the operation sequence is shifted in. Table 4–8 shows the operation sequence for every operation supported by the serial configuration devices.

For the read byte, read status, and read silicon ID operations, the shifted-in operation sequence is followed by data shifted out on the DATA pin. You can drive the nCS pin high after any bit of the data-out sequence is shifted out.

For the write byte, erase bulk, erase sector, write enable, write disable, and write status operations, drive the nCS pin high exactly at a byte boundary (drive the nCS pin high a multiple of eight clock pulses after the nCS pin was driven low). Otherwise, the operation is rejected and will not be executed.

All attempts to access the memory contents while a write or erase cycle is in progress will not be granted, and the write or erase cycle will continue unaffected.

Table 4–8. Operation Codes for Serial Configuration Devices

| Operation	Operation Code *(1)*	Address Bytes	Dummy Bytes	Data Bytes	DCLK f$_{MAX}$ (MHz)
Write enable	`0000 0110`	0	0	0	25
Write disable	`0000 0100`	0	0	0	25
Read status	`0000 0101`	0	0	1 to infinite *(2)*	25
Read bytes	`0000 0011`	3	0	1 to infinite *(2)*	20
Read silicon ID	`1010 1011`	0	3	1 to infinite *(2)*	25
Write status	`0000 0001`	0	0	1	25
Write bytes	`0000 0010`	3	0	1 to 256 *(3)*	25
Erase bulk	`1100 0111`	0	0	0	25
Erase sector	`1101 1000`	3	0	0	25

Notes to Table 4–8:
(1) The MSB is listed first and the least significant bit (LSB) is listed last.
(2) The status register, data or silicon ID are read out at least once on the `DATA` pin and will continuously be read out until `nCS` is driven high
(3) Write bytes operation requires at least one data byte on the `DATA` pin. If more than 256 bytes are sent to the device, only the last 256 bytes are written to the memory.

Write Enable Operation

The write enable operation code is b'0000 0110, and the most significant bit is listed first. The write enable operation sets the write enable latch bit, which is bit 1 in the status register. Always set the write enable latch bit before write bytes, write status, erase bulk, and erase sector operations. Figure 4–5 shows the timing diagram for the write enable operation. Figures 4–7 and 4–8 show the status register bit definitions.

Figure 4–5. Write Enable Operation Timing Diagram
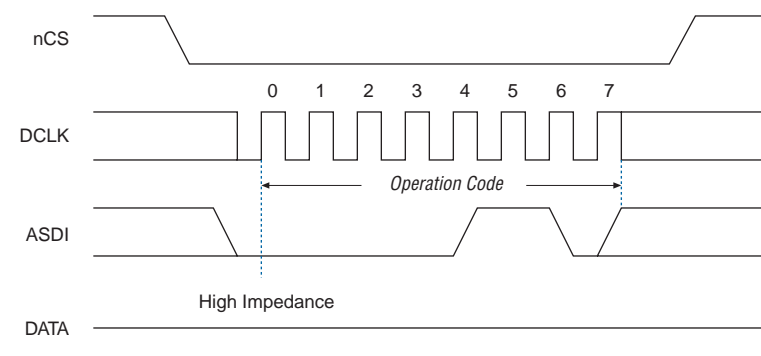
Write Disable Operation

The write disable operation code is b'0000 0100, with the MSB listed first. The write disable operation resets the write enable latch bit, which is bit 1 in the status register. To prevent the memory from being written unintentionally, the write enable latch bit is automatically reset when implementing the write disable operation as well as under the following conditions:

■ Power up
■ Write bytes operation completion
■ Write status operation completion
■ Erase bulk operation completion
■ Erase sector operation completion

Figure 4–6 shows the timing diagram for the write disable operation.

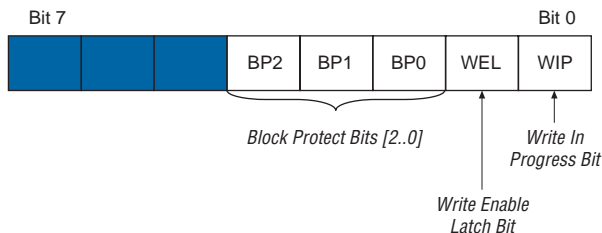*Figure 4–6. Write Disable Operation Timing Diagram*
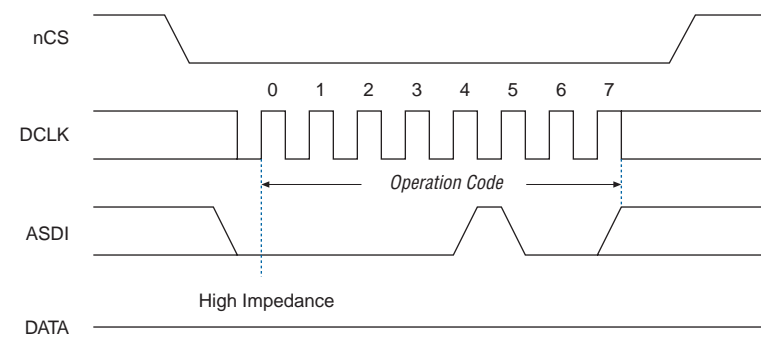
Read Status Operation

The read status operation code is b'0000 0101, with the MSB listed first. You can use the read status operation to read the status register. Figures 4–7 and 4–8 show the status bits in the status register of both serial configuration devices.

Figure 4–7. EPCS4 Status Register Status Bits

Figure 4–8. EPCS1 Status Register Status Bits
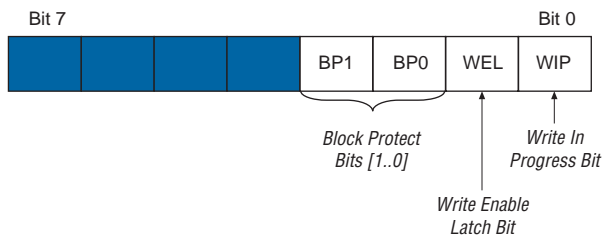
Setting the write in progress bit to 1 indicates that the serial configuration device is busy with a write or erase cycle. Resetting the write in progress bit to 0 means no write or erase cycle is in progress.

Resetting the write enable latch bit to 0 indicates that no write or erase cycle will be accepted. Set the write enable latch bit to 1 before every write bytes, write status, erase bulk, and erase sector operation.

The non-volatile block protect bits determine the area of the memory protected from being written or erased unintentionally. Tables 4–9 and 4–10 show the protected area in both serial configuration devices with reference to the block protect bits. The erase bulk operation is only

available when all the block protect bits are 0. When any of the block protect bits are set to one, the relevant area is protected from being written by write bytes operations or erased by erase sector operations.

Table 4–9. Block Protection Bits in EPCS4 Devices

Status Register Content			Memory Content	
BP2 Bit	**BP1 Bit**	**BP0 Bit**	**Protected Area**	**Unprotected Area**
0	0	0	None	All eight sectors: 0 to 7
0	0	1	Sector 7	Seven sectors: 0 to 6
0	1	0	Sectors 6 and 7	Six sectors: 0 to 5
0	1	1	Four sectors: 4 to 7	Four sectors: 0 to 3
1	0	0	All sectors	None
1	0	1	All sectors	None
1	1	0	All sectors	None
1	1	1	All sectors	None

Table 4–10. Block Protection Bits in EPCS1

Status Register Content		Memory Content	
BP1 Bit	**BP0 Bit**	**Protected Area**	**Unprotected Area**
0	0	None	All four sectors: 0 to 3
0	1	Sector 3	Three sectors: 0 to 2
1	0	Two sectors: 2 and 3	Two sectors: 0 and 1
1	1	All sectors	None

The status register can be read at any time, even while a write or erase cycle is in progress. When one of these cycles is in progress, you can check the write in progress bit (bit 0 of the status register) before sending a new operation to the device. The device can also read the status register continuously, as shown in Figure 4–9.

Figure 4–9. Read Status Operation Timing Diagram
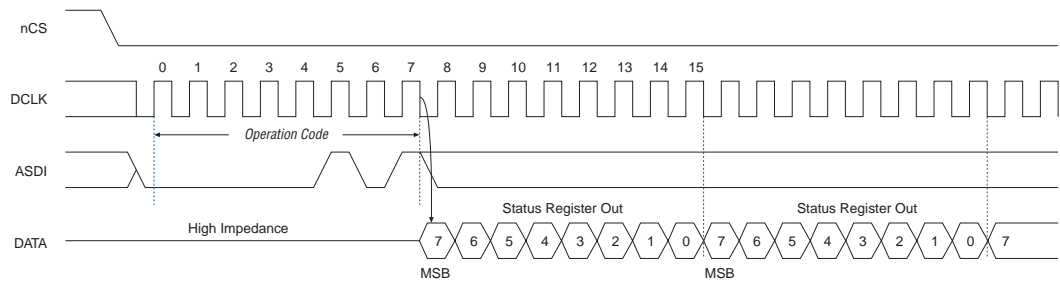
Write Status Operation

The write status operation code is b'0000 0001, with the MSB listed first. Use the write status operation to set the status register block protection bits. The write status operation has no effect on the other bits. Therefore, designers can implement this operation to protect certain memory sectors, as defined in Tables 4–9 and 4–10. After setting the block protect bits, the protected memory sectors are treated as read-only memory. Designers must execute the write enable operation before the write status operation so the device sets the status register's write enable latch bit to 1.

The write status operation is implemented by driving nCS low, followed by shifting in the write status operation code and one data byte for the status register on the ASDI pin. Figure 4–10 shows the timing diagram for the write status operation. nCS must be driven high after the eighth bit of the data byte has been latched in, otherwise, the write status operation is not executed.

Immediately after nCS is driven high, the device initiates the self-timed write status cycle. The self-timed write status cycle usually takes 5 ms for both serial configuration devices and is guaranteed to be less than 15 ms (see t_{WS} in Table 4–12). Designers must account for this delay to ensure that the status register is written with desired block protect bits. Alternatively, you can check the write in progress bit in the status register by executing the read status operation while the self-timed write status cycle is in progress. The write in progress bit is 1 during the self-timed write status cycle, and is 0 when it is complete.

Figure 4–10. Write Status Operation Timing Diagram
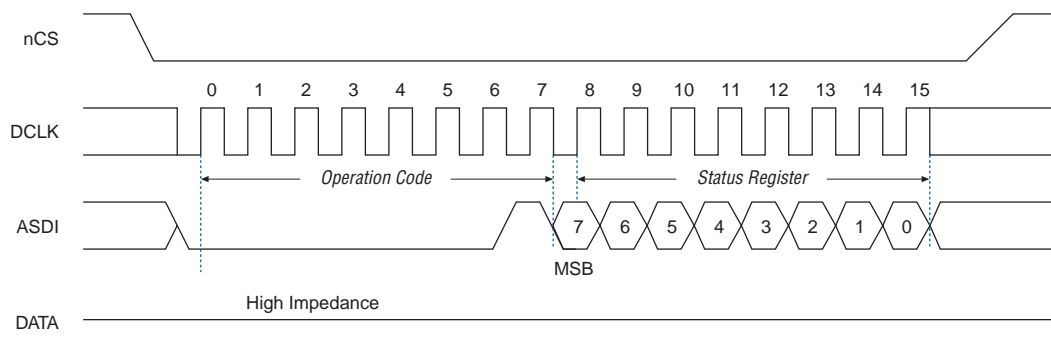
Read Bytes Operation

The read bytes operation code is b'0000 0011, with the MSB listed first. To read the memory contents of the serial configuration device, the device is first selected by driving nCS low. Then, the read bytes operation code is shifted-in followed by a 3-byte address (A[23..0]). Each address bit must be latched-in on the rising edge of the DCLK. After the address is latched in, the memory contents of the specified address are shifted out serially on the DATA pin, beginning with the MSB. Each data bit is shifted out on the falling edge of DCLK. The maximum DCLK frequency during the read bytes operation is 20 MHz. Figure 4–11 shows the timing diagram for read bytes operation.

The first byte addressed can be at any location. The device automatically increments the address to the next higher address after shifting out each byte of data. Therefore, the device can read the whole memory with a single read bytes operation. When the device reaches the highest address, the address counter restarts at 0x000000, allowing the memory contents to be read out indefinitely until the read bytes operation is terminated by driving nCS high. The device can drive nCS high any time after data is shifted out. If the read bytes operation is shifted in while a write or erase cycle is in progress, the operation will not be executed. Additionally, it will not have any effect on the write or erase cycle in progress.

Figure 4–11. Read Bytes Operation Timing Diagram
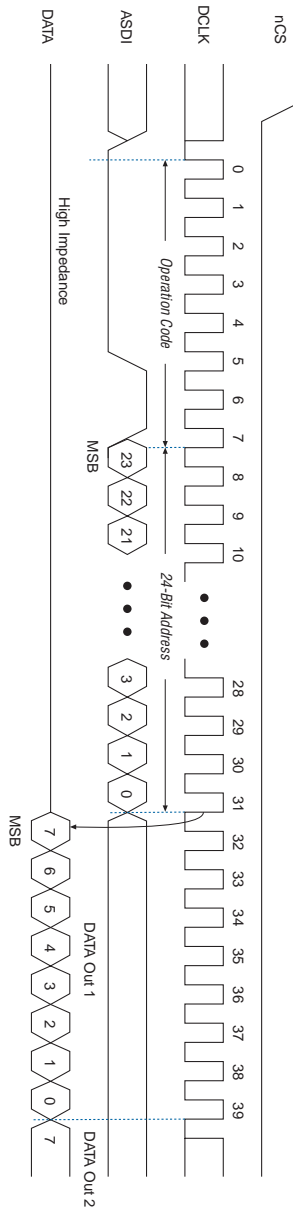
Note to Figure 4–11:
(1)   Address bits A[23..19] are don't care bits in the EPCS4 device. Address bits A[23..17] are don't care bits in the EPCS1 device.

Read Silicon ID Operation

The read silicon ID operation code is b'1010 1011, with the MSB listed first. This operation reads the serial configuration device's 8-bit silicon ID from the DATA output pin. If this operation is shifted in during an erase or write cycle, it will be ignored and have no effect on the cycle that is in progress. Table 4–11 shows the EPCS1 and EPCS4 device silicon IDs.

Table 4–11. Serial Configuration Device Silicon ID	
Serial Configuration Device	**Silicon ID (Binary Value)**
EPCS1	b'0001 0000
EPCS4	b'0001 0010

The device implements the read silicon ID operation by driving nCS low then shifting in the read silicon ID operation code followed by three dummy bytes on ASDI. The serial configuration device's 8-bit silicon ID is then shifted out on the DATA pin on the falling edge of DCLK, as shown in Figure 4–12. The device can terminate the read silicon ID operation by driving nCS high after the silicon ID has been read at least once. Sending additional clock cycles on DCLK while nCS is driven low can cause the silicon ID to be shifted out repeatedly.

Figure 4–12. Read Silicon ID Operation Timing Diagram
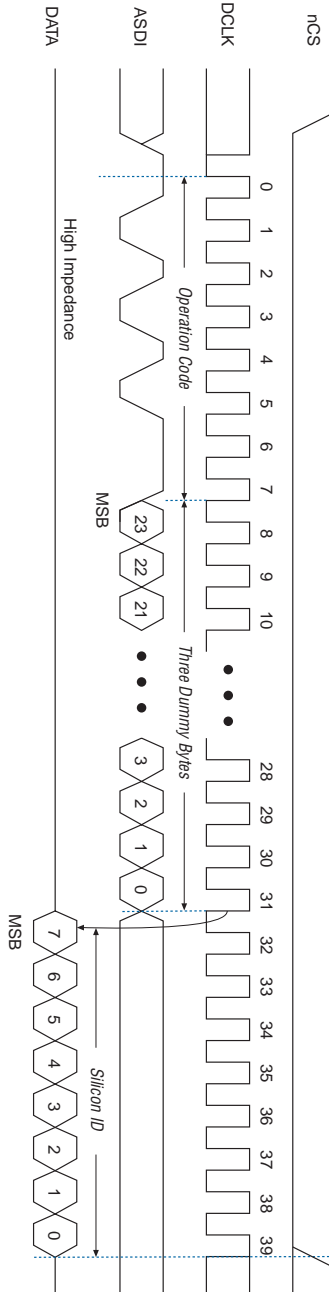
Write Bytes Operation

The write bytes operation code is b'0000 0010, with the MSB listed first. The write bytes operation allows bytes to be written to the memory. The write enable operation must be executed prior to the write bytes operation to set the write enable latch bit in the status register to 1.

The write bytes operation is implemented by driving nCS low, followed by the write bytes operation code, three address bytes and a minimum one data byte on ASDI. If the eight least significant address bits (A[7..0]) are not all 0, all sent data that goes beyond the end of the current page is not written into the next page. Instead, this data is written at the start address of the same page (from the address whose eight LSBs are all 0). Drive nCS low during the entire write bytes operation sequence as shown in Figure 4–13.

If more than 256 data bytes are shifted into the serial configuration device with a write bytes operation, the previously latched data is discarded and the last 256 bytes are written to the page. However, if less than 256 data bytes are shifted into the serial configuration device, they are guaranteed to be written at the specified addresses and the other bytes of the same page are unaffected.

If the design must write more than 256 data bytes to the memory, it needs more than one page of memory. Send the write enable and write bytes operation codes followed by three new targeted address bytes and 256 data bytes before a new page is written.

nCS must be driven high after the eighth bit of the last data byte has been latched in. Otherwise, the device will not execute the write bytes operation. The write enable latch bit in the status register is reset to 0 before the completion of each write bytes operation. Therefore, the write enable operation must be carried out before the next write bytes operation.

The device initiates the self-timed write cycle immediately after nCS is driven high. The self-timed write cycle usually takes 1.5 ms for EPCS4 devices and 2 ms for EPCS1 devices and is guaranteed to be less than 5 ms (see t_{WB} in Table 4–12). Therefore, the designer must account for this amount of delay before another page of memory is written. Alternatively, the designer can check the status register's write in progress bit by executing the read status operation while the self-timed write cycle is in progress. The write in progress bit is set to 1 during the self-timed write cycle, and is 0 when it is complete.

Figure 4–13. Write Bytes Operation Timing Diagram
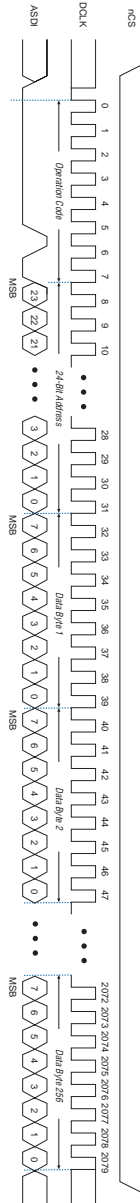
Note to Figure 4–13:

(1)   Address bits `A[23..19]` are don't care bits in the PCS4 device. Address bits `A[23..17]` are the don't care bits in the EPCS1 device.

Erase Bulk Operation

The erase bulk operation code is b'1100 0111, with the MSB listed first. The erase bulk operation sets all memory bits to 1 or 0xFF. Similar to the write bytes operation, the write enable operation must be executed prior to the erase bulk operation so that the write enable latch bit in the status register is set to 1.

Designers implement the erase bulk operation by driving nCS low and then shifting in the erase bulk operation code on the ASDI pin. nCS must be driven high after the eighth bit of the erase bulk operation code has been latched in. Figure 4–14 shows the timing diagram.

The device initiates the self-timed erase bulk cycle immediately after nCS is driven high. The self-timed erase bulk cycle usually takes 5 s for EPCS4 devices (guaranteed to be less than 10 s) or 3 s for EPCS1 devices (guaranteed to be less than 6 s). See t_{EB} in Table 4–12. Designers must account for this delay before accessing the memory contents. Alternatively, designers can check the write in progress bit in the status register by executing the read status operation while the self-timed erase cycle is in progress. The write in progress bit is 1 during the self-timed erase cycle and is 0 when it is complete. The write enable latch bit in the status register is reset to 0 before the erase cycle is complete.

Figure 4–14. Erase Bulk Operation Timing Diagram
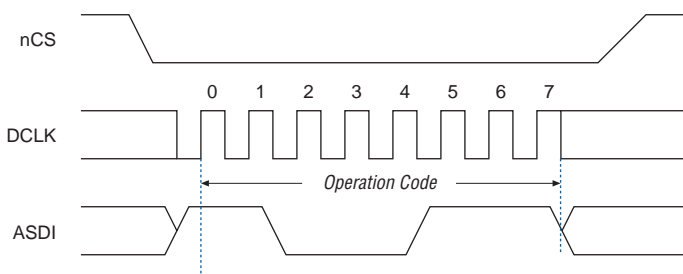
Erase Sector Operation

The erase sector operation code is b'1101 1000, with the MSB listed first. The erase sector operation allows the user to erase a certain sector in the serial configuration device by setting all bits inside the sector to 1 or 0xFF. This operation is useful for users who access the unused sectors as general purpose memory in their applications.

The write enable operation must be executed prior to the erase sector operation so that the write enable latch bit in the status register is set to 1.

The erase sector operation is implemented by first driving nCS low, then shifting in the erase sector operation code and the three address bytes of the chosen sector on the ASDI pin. The three address bytes for the erase sector operation can be any address inside the specified sector. (See Tables 4–6 and 4–7 for sector address range information.) Drive nCS high after the eighth bit of the erase sector operation code has been latched in. Figure 4–15 shows the timing diagram.

Immediately after the device drives nCS high, the self-timed erase sector cycle is initiated. The self-timed erase sector cycle usually takes 2 s for EPCS1 and EPCS4 devices and is guaranteed to be less than 3 s for both serial configuration devices. You must account for this amount of delay before the memory contents can be accessed. Alternatively, you can check the write in progress bit in the status register by executing the read status operation while the erase cycle is in progress. The write in progress bit is 1 during the self-timed erase cycle and is 0 when it is complete. The write enable latch bit in the status register is reset to 0 before the erase cycle is complete.

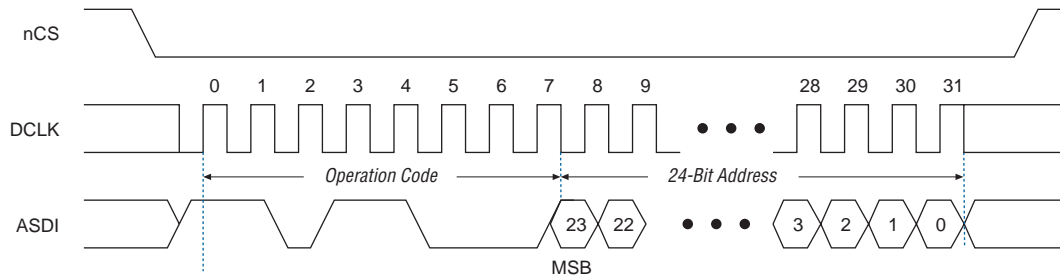*Figure 4–15. Erase Sector Operation Timing Diagram*

Power & Operation

This section describes the power modes, power-on reset (POR) delay, error detection, and initial programming state of serial configuration devices.

Power Mode

Serial configuration devices support active power and standby power modes. When nCS is low, the device is enabled and is in active power mode. The FPGA is configured while in active power mode. When nCS is high, the device is disabled but could remain in active power mode until all internal cycles have completed (such as write or erase operations). The serial configuration device then goes into stand-by power mode. The I_{CC1}

parameter specifies the V_{CC} supply current when the device is in active power mode and the I_{CC0} parameter specifies the current when the device is in stand-by power mode (see Table 4–18).

Power-On Reset

During initial power-up, a POR delay occurs to ensure the system voltage levels have stabilized. During AS configuration, the FPGA controls the configuration and has a longer POR delay than the serial configuration device. Therefore, the POR delay is governed by the Stratix II FPGA (typically 12 ms or 100 ms) or Cyclone series FPGA (typically 100 ms).

Error Detection

During AS configuration with the serial configuration device, the FPGA monitors the configuration status through the nSTATUS and CONF_DONE pins. If an error condition occurs (nSTATUS drives low) or if the CONF_DONE pin does not go high, the FPGA will initiate reconfiguration by pulsing the nSTATUS and nCSO signals, which controls the chip select pin on the serial configuration device (nCS).

After an error, configuration automatically restarts if the *Auto-Restart Upon Frame Error* option is turned on in the Quartus II software. If the option is turned off, the system must monitor the nSTATUS signal for errors and then pulse the nCONFIG signal low to restart configuration.

Timing Information

Figure 4–16 shows the timing waveform for write operation to the serial configuration device.
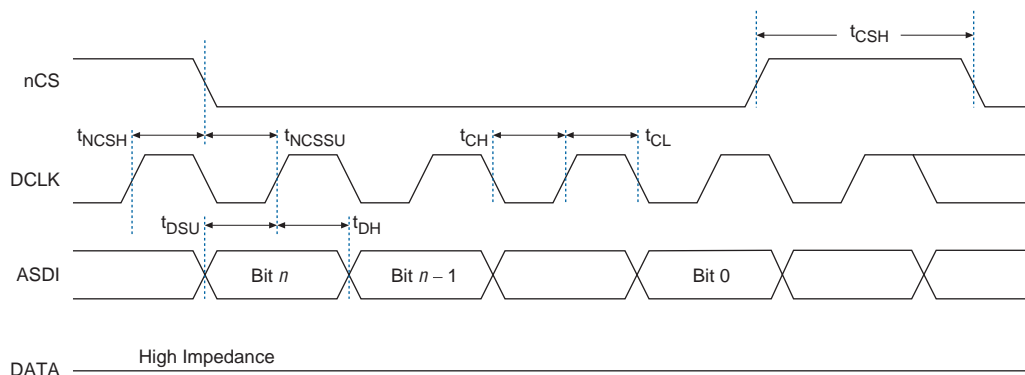
Figure 4–16. Write Operation Timing

Table 4–12 defines the serial configuration device timing parameters for write operation.

Table 4–12. Write Operation Parameters					
Symbol	**Parameter**	**Min**	**Max**	**Unit**
f_{WCLK}	Write clock frequency (from FPGA, download cable, or embedded processor) for write enable, write disable, read status, read silicon ID, write bytes, erase bulk, and erase sector operations		25	MHz
t_{CH}	DCLK high time	20		ns
t_{CL}	DCLK low time	20		ns
t_{NCSSU}	Chip select (nCS) setup time	10		ns
t_{NCSH}	Chip select (nCS) hold time	10		ns
t_{DSU}	Data (ASDI) in setup time before rising edge on DCLK	5		ns
t_{DH}	Data (ASDI) hold time after rising edge on DCLK	5		ns
t_{CSH}	Chip select high time	100		ns
t_{WB_EPCS1} (1)	Write bytes cycle time for EPCS1 devices	2	5	ms
t_{WB_EPCS4} (1)	Write bytes cycle time for EPCS4 devices	1.5	5	ms
t_{WS} (1)	Write status cycle time	5	15	ms
t_{EB_EPCS1} (1)	Erase bulk cycle time for EPCS1 devices	3	6	s
t_{EB_EPCS4} (1)	Erase bulk cycle time for EPCS4 devices	5	10	s
t_{ES} (1)	Erase sector cycle time	2	3	s

Note to Table 4–12:
(1)   These parameters are not shown in Figure 4–16.

Figure 4–17 shows the timing waveform for the serial configuration device's read operation.

Figure 4–17. Read Operation Timing
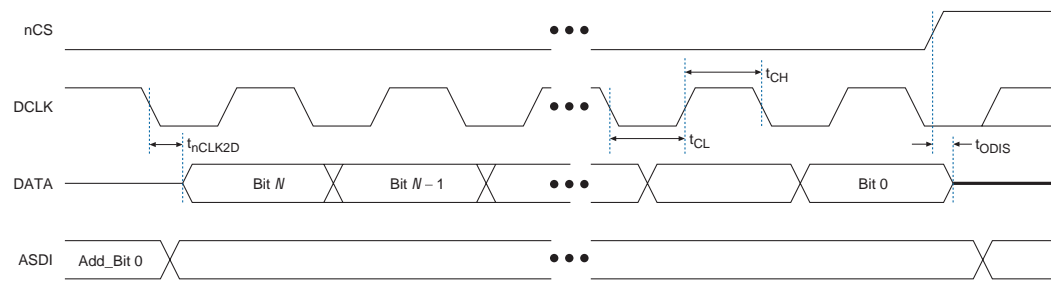
Table 4–13 defines the serial configuration device timing parameters for read operation.

Table 4–13. Read Operation Parameters				
Symbol	**Parameter**	**Min**	**Max**	**Unit**
f_{RCLK}	Read clock frequency (from FPGA or embedded processor) for read bytes operation		20	MHz
t_{CH}	`DCLK` high time	25		ns
t_{CL}	`DCLK` low time	25		ns
t_{ODIS}	Output disable time after read		15	ns
t_{nCLK2D}	Clock falling edge to data		15	ns

Figure 4–18 shows the timing waveform for FPGA AS configuration scheme using a serial configuration device.
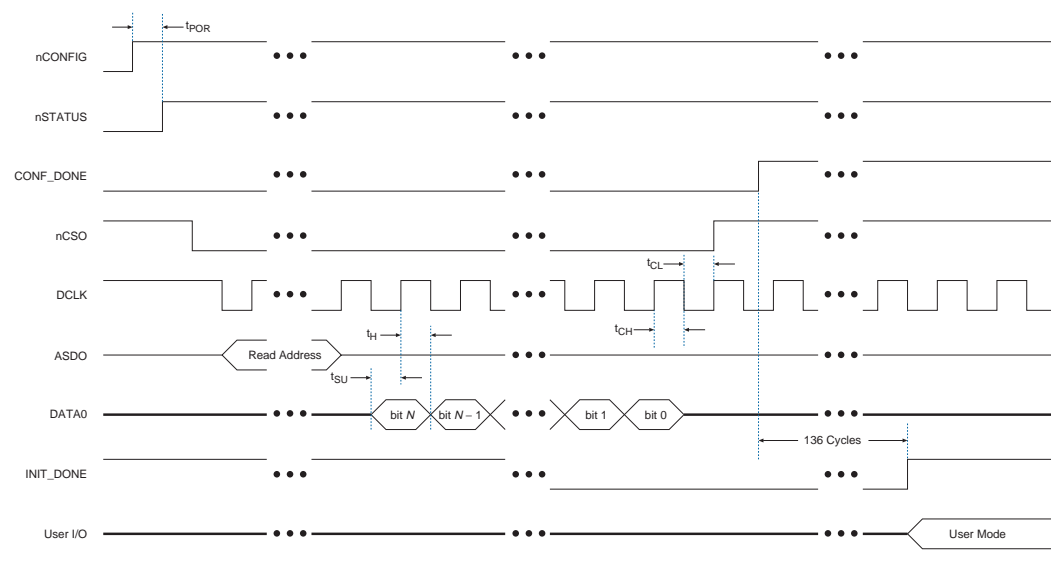
Figure 4–18. AS Configuration Timing

Table 4–14 shows the timing parameters for AS configuration mode.

Table 4–14. Timing Parameters for AS Configuration					
Symbol	**Parameter**	**Min**	**Typ**	**Max**	**Unit**
f_{CLK}	DCLK frequency from Cyclone FPGA	14	17	20	MHz
f_{CLK}	DCLK frequency from Stratix II or Cyclone II FPGA (1)	20 (2)	26 (2)	40 (2)	MHz
		10	13	20	MHz
t_{CH}	DCLK high time	25			ns
t_{CL}	DCLK low time	25			ns
t_{H}	Data hold time after rising edge on DCLK	0			ns
t_{SU}	Data set up time before rising edge on DCLK	5			ns
t_{POR}	POR delay			100	ms

Notes to Table 4–14:
(1)   These values are preliminary
(2)   Only the EPCS16 and EPCS64 devices support a DCLK frequency up to 40 MHz.

Programming & Configuration File Support

The Quartus II design software provides programming support for serial configuration devices. After selecting the serial configuration device, the Quartus II software automatically generates the Programmer Object File (**.pof**) to program the device. The software allows users to select the appropriate serial configuration device density that most efficiently stores the configuration data for a selected FPGA.

The serial configuration device can be programmed in-system by an external microprocessor using SRunner. SRunner is a software driver developed for embedded serial configuration device programming that designers can customize to fit in different embedded systems. The SRunner can read a Raw Programming Data file (**.rpd**) and write to the serial configuration devices. The programming time is comparable to the Quartus II software programming time.

For more information about SRunner, see the *SRunner: An Embedded Solution for Serial Configuration Device Programming White Paper* and the source code on the Altera web site (**www.altera.com**).

Serial configuration devices can be programmed using the APU with the appropriate programming adapter (PLMSEPC-8 or PLMSEPC-16) via the Quartus II software, USB Blaster, or the ByteBlaster II download cable via the Quartus II software. In addition, many third-party programmers, such as BP Microsystems and System General, offer programming hardware that supports serial configuration devices.

During in-system programming of a serial configuration device via the USB Blaster or ByteBlaster II download cable, the cable pulls nCONFIG low to reset the FPGA and overrides the 10-kΩ pull-down resistor on the FPGA's nCE pin (see Figure 4–2). The download cable then uses the four interface pins (DATA, nCS, ASDI, and DCLK) to program the serial configuration device. Once the programming is complete, the download cable releases the serial configuration device's four interface pins and the FPGA's nCE pin, and pulses nCONFIG to start configuration.

For more information on programming and configuration support, see the following documents:

- *Altera Programming Hardware Data Sheet*
- *Programming Hardware Manufacturers*
- *USB Blaster USB Port Download Cable Development Tools Data Sheet*
- *ByteBlaster II Parallel Port Download Cable Data Sheet*

Operating Conditions

Tables 4–15 through 4–19 provide information on absolute maximum ratings, recommended operating conditions, DC operating conditions, and capacitance for serial configuration devices.

Table 4–15. Absolute Maximum Ratings   *Note (1)*

Symbol	Parameter	Condition	Min	Max	Unit
V_{CC}	Supply voltage	With respect to ground	−0.6	4.0	V
V_I	DC input voltage	With respect to ground	−0.6	4.0	V
I_{MAX}	DC V_{CC} or GND current			15	mA
I_{OUT}	DC output current per pin		−25	25	mA
P_D	Power dissipation			54	mW
T_{STG}	Storage temperature	No bias	−65	150	°C
T_{AMB}	Ambient temperature	Under bias	−65	135	°C
T_J	Junction temperature	Under bias		135	°C

Table 4–16. Recommended Operating Conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	Supply voltage	*(2)*	3.0	3.6	V
V_I	Input voltage	Respect to GND	−0.3	$0.3 + V_{CC}$	V
V_O	Output voltage		0	V_{CC}	V
T_A	Operating temperature	For commercial use	0	70	°C
		For industrial use	−40	85	°C
t_R	Input rise time			5	ns
t_F	Input fall time			5	ns

Table 4–17. DC Operating Conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{IH}	High-level input voltage		$0.7 \times V_{CC}$	$V_{CC} + 0.4$	V
V_{IL}	Low-level input voltage		−0.5	$0.3 \times V_{CC}$	V
V_{OH}	High-level output voltage	$I_{OH} = -100\ \mu A$ *(3)*	$V_{CC} -0.2$		V
V_{OL}	Low-level output voltage	$I_{OL} = 1.6\ mA$ *(3)*		0.4	V
I_I	Input leakage current	$V_I = V_{CC}$ or GND	−10	10	μA
I_{OZ}	Tri-state output off-state current	$V_O = V_{CC}$ or GND	−10	10	μA

Table 4–18. I_{CC} Supply Current

Symbol	Parameter	Conditions	Min	Max	Unit
I_{CC0}	V_{CC} supply current (standby)			50	µA
I_{CC1}	V_{CC} supply current (during active power mode)		5	14	mA

Table 4–19. Capacitance   *Note (4)*

| Symbol	Parameter	Conditions	Min	Max	Unit
C_{IN}	Input pin capacitance	V_{IN} = 0 V		6	pF
C_{OUT}	Output pin capacitance	V_{OUT} = 0 V		8	pF

Notes to Table 4–15 through 4–19:

(1) See the *Operating Requirements for Altera Devices Data Sheet*.

(2) Maximum V_{CC} rise time is 100 ms.

(3) The I_{OH} parameter refers to high-level TTL or CMOS output current; the I_{OL} parameter refers to low-level TTL or CMOS output current.

(4) Capacitance is sample-tested only at T_A = 25 °C and at a 20-MHz frequency.

Pin Information

As shown in Figure 4–19, the serial configuration device is an 8-pin or 16-pin device. The control pins on the serial configuration device are: serial data output (DATA), active serial data input (ASDI), serial clock (DCLK), and chip select (nCS). Table 4–20 shows the serial configuration device's pin descriptions.

Figure 4–19 shows the Altera serial configuration device 8-pin SOIC package and its pin-out diagram.

Figure 4–19. Altera Serial Configuration Device 8-Pin SOIC Package Pin-Out Diagram
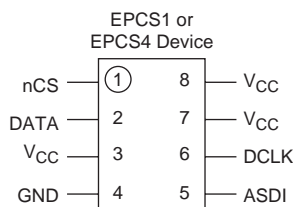
Figure 4–20 shows the Altera serial configuration device 16-pin SOIC package and its pin-out diagram.

Figure 4–20. Altera Serial Configuration Device 16-Pin SOIC Package Pin-Out Diagram
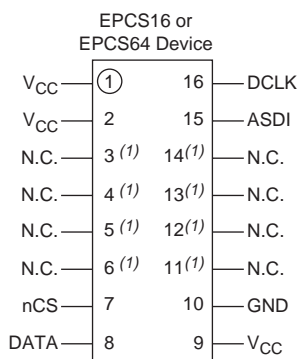
Note to Figure 4–20:
(1) These pins can be left floating or connected to V_{cc} or GND, whichever is more convenient on the board.

Table 4–20. Serial Configuration Device Pin Description

Pin Name	Pin Number	Pin Type	Description
DATA	2	Output	The DATA output signal transfers data serially out of the serial configuration device to the FPGA during read/configuration operation. During a read/configuration operations, the serial configuration device is enabled by pulling nCS low. The DATA signal transitions on the falling edge of DCLK.
ASDI	5	Input	The AS data input signal is used to transfer data serially into the serial configuration device. It receives the data that should be programmed into the serial configuration device. Data is latched in the rising edge of DCLK.
nCS	1	Input	The active low chip select input signal toggles at the beginning and end of a valid instruction. When this signal is high, the device is deselected and the DATA pin is tri-stated. When this signal is low, it enables the device and puts the device in an active mode. After power up, the serial configuration device requires a falling edge on the nCS signal before beginning any operation.
DCLK	6	Input	DCLK is provided by the FPGA. This signal provides the timing of the serial interface. The data presented on ASDI is latched to the serial configuration device, at the rising edge of DCLK. Data on the DATA pin changes after the falling edge of DCLK and is latched into the FPGA on the rising edge.
VCC	3, 7, 8	Power	Power pins connect to 3.3 V.
GND	4	Ground	Ground pin.

Package

All serial configuration devices are available in 8-pin or 16-pin plastic SOIC package.

For more information on Altera device packaging including mechanical drawing and specifications for this package, see the *Altera device Package Information Data Sheet*.

Ordering Code

Table 4–21 shows the ordering codes for serial configuration devices.

Table 4–21. Serial Configuration Device Ordering Codes	
Device	**Ordering Code**
EPCS1	EPCS1SI8N
EPCS4	EPCS4SI8N
EPCS16	EPCS16SI16N *(1)*
EPCS64	EPCS64SI16N *(1)*

Notes to Table 4–21:
(1)   These devices will not be available until the second half of 2004.